ON Semiconductor

Initial Product/Process Change Notification

Document # : IPCN20950X
Issue Date: 1 July 2015

Title of Change:	Copper wire conversion and mold compound change for LB1936V and LB1973JA.
Proposed first ship date:	23 November 2015
Contact information:	Contact your local ON Semiconductor Sales Office or < Tsutomu Shimazaki@onsemi.com > < Takashi.Harashima@onsemi.com>< Takeshi2.Hoshino@onsemi.com>< Kazumi.Onda@onsemi.com> < Shinya Okada@onsemi.com>< Yoshiyuki Nunokawa@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or < jun.hasunuma@onsemi.com>
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with date code
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☒ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable
☒ ON Semiconductor site(s) : ON Tarlac City, Philippines
☐ External Foundry/Subcon site(s)

Description and Purpose:

This is an Initial Process Change Notification for the content below:

1) Gold wire connecting chip and Lead will be changed to Copper wire.
2) Mold resin will be changed to suitable for Copper wire.

Electrical characteristic specifications are not impacted of this change.

Qualification Plan:

Estimated date for qualification completion: 28 August 2015

Package name : SSOP16(225mil)

Test Items	Test Condition	Test Time
High Temperature Operating Life	Tj=Tjmax,Vcc=Operatingmax	1000hrs
Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended T	1000hrs
Temperature Cycle *	Ta=-65degC(30min) ⇔ Ta=150degC (30min)	500cycles
Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	50hrs
High Temperature Storage	Ta=150degC	1000hrs
Resistance to Soldering heat (Reflow Soldering)	255degC,10s (Peak260degC)	2times

Notes:
The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD
Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.
Judgment Criteria :
Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

List of Affected Standard Parts:	
Part Number	**Qualification Vehicle**
LB1936V-TLM-E	LB1936V-TLM-E
LB1973JA-AH	LB1936V-TLM-E